

### Stock Symbol: 3167

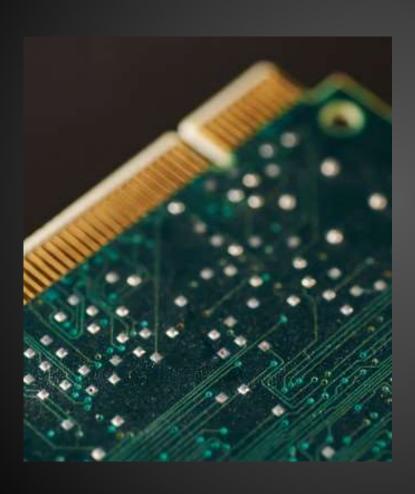




#### Disclaimer

- The predictive information mentioned in this presentation, including operational outlook, business situation, etc., is obtained by the Company through internal and external sources.
- The company's actual operational results that may occur in the future due to factors including but not limited to market competition and the conditions of international economy.
- The outlook for the future in this presentation is the Company's external views until now. For these views, if there are updates or adjustments in the future, the Company is not responsible for reminding or updating again at any time.





# Company Profile

# Company Overview

Stock Symbol	3167
Capital	NTD 825,381,400
Chairman	Laurie Wang
General manager	Jackie Chien
Headquarter	No. 68, Fengtian Rd., Bade Dist.Taoyuan City, Taiwan (R.O.C.)
Factories	Bade ` Nanjing ` Lianshui





- Standard & High end PCB Drilling Machine
- Standard & High end PCB Routing Machine
- Automation
- Others

**PCB Industry** 



- Metrology Series
- AOI Series
- Automation Series

Semi con. Industry



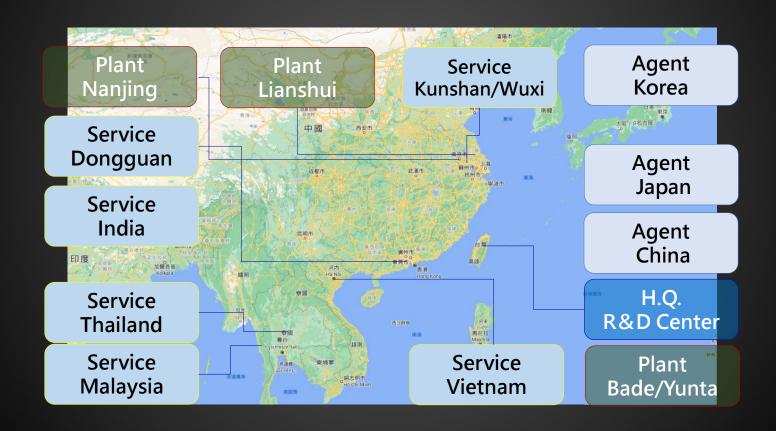
• R&D/purchasing/production/sales/service/management

TL Technology Team





### Production & Service Base







# PCB main products





standard

1



**CCD** series

**PCB Router** 



standard



**CCD** series



depth control

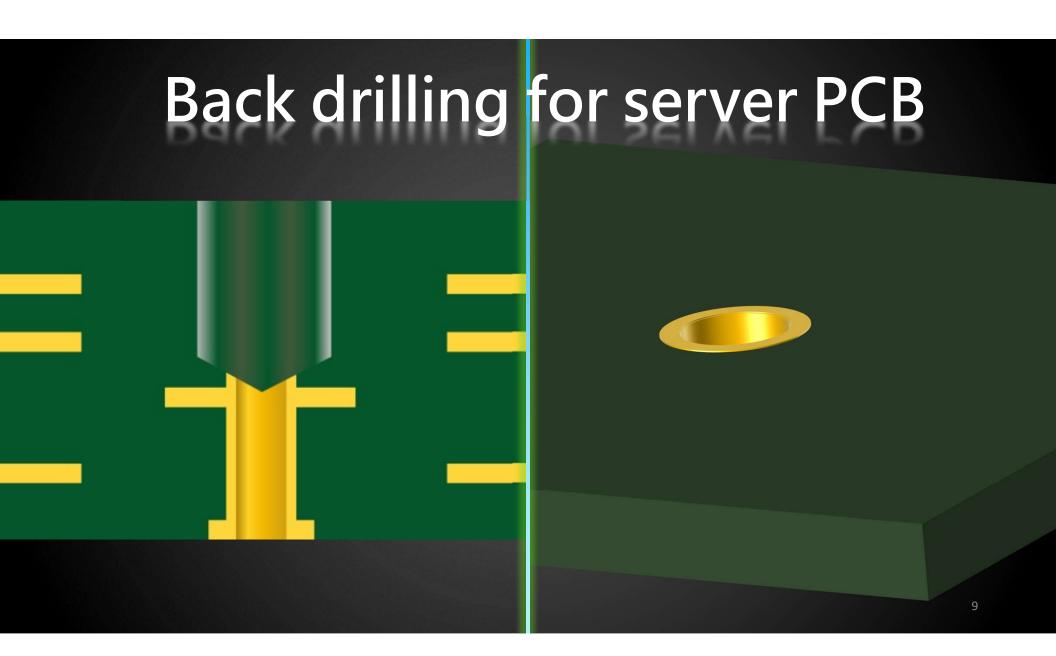
**PCB** Automation



barcode drilling

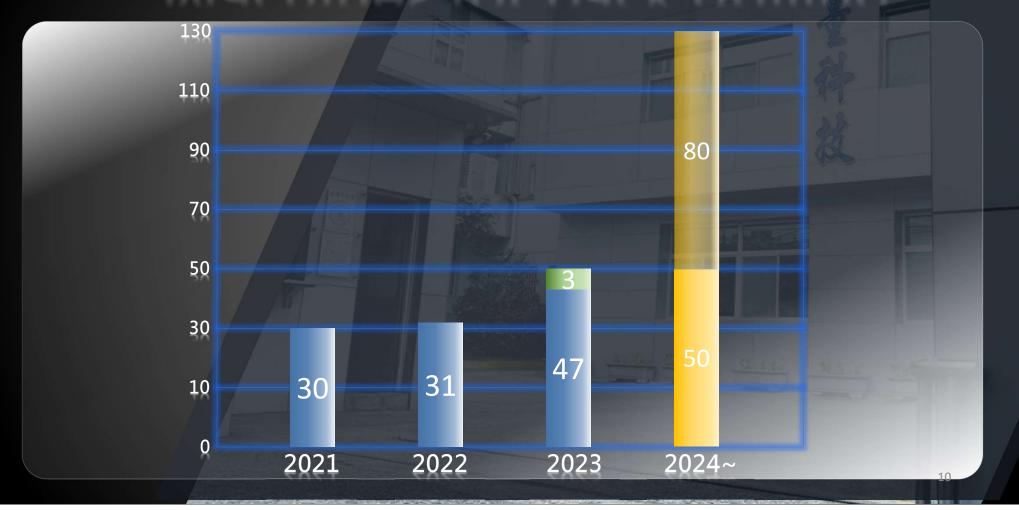


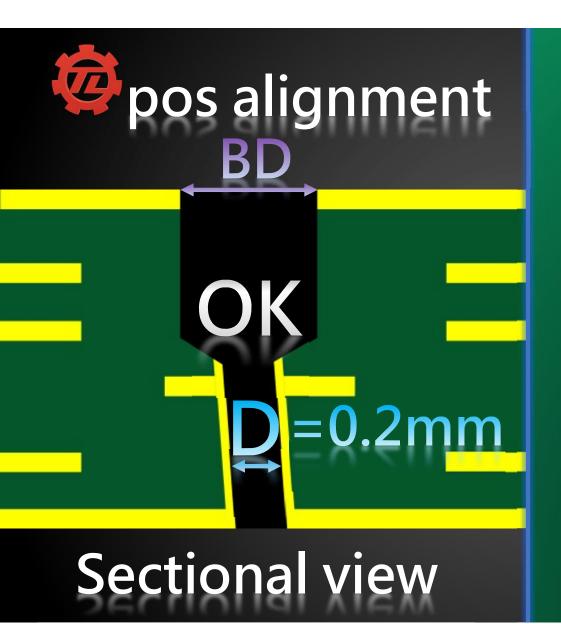
6-spindles drilling machine





## Machines for back drilling





 $4mil \times 0.025 = 0.1mm$ BD=D+4mil

BD=0.3mmtop view



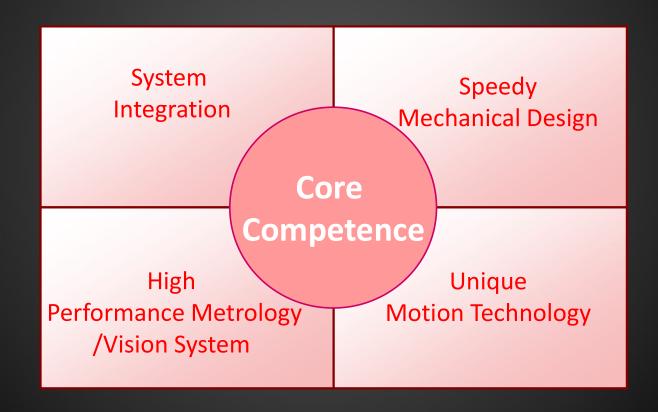
### stub length spec



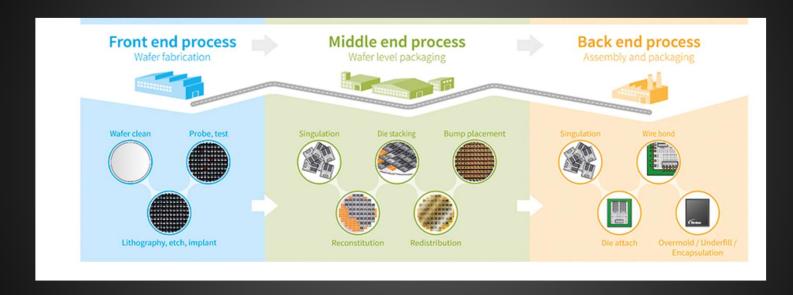


# TA LIANG Technology Semiconductor BU

## Core Competence



# Product Line-up



- CMP Pad Metrology
- Metrology Series

- Metrology Series
- AOI Series
- Automation Series

## 3D IC Solution-Chip Stacking(FE 3D)

#### **CMP Pad Metrology**



Step-height Metrology



#### **Bonding Wafer Metrology**





# 3D IC Solution-Advanced Package(BE 3D)

#### **Thermal Optical AOI**



#### **Flux Jetting AOI**



#### **Die Bond AOI**



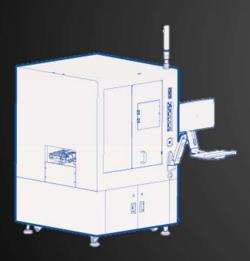


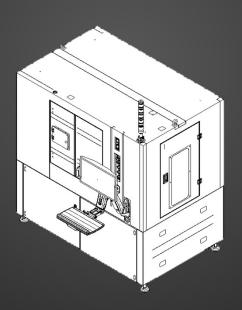
# 3D IC Solution-Advanced Package(FO 3D)

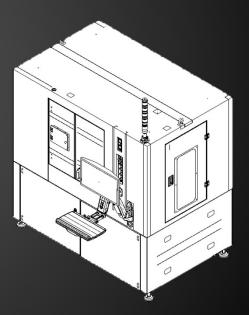
Wafer D/B AOI

Wafer U/F AOI (+Fillet-height)

Wafer Edge Die AOI





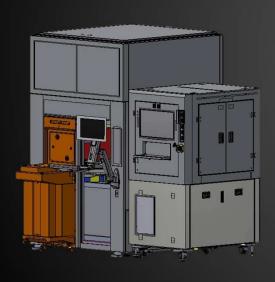




Wafer Molding AOI/ Metrology

**Wafer Warp Metrology** 

R2R AOI(FVI)









# For Flip Chip & WLCSP Solution-AOI

#### Flux Jetting AOI



#### F/C Bond AOI



#### IPD AOI



#### **SMD AOI**





#### **Customer List**















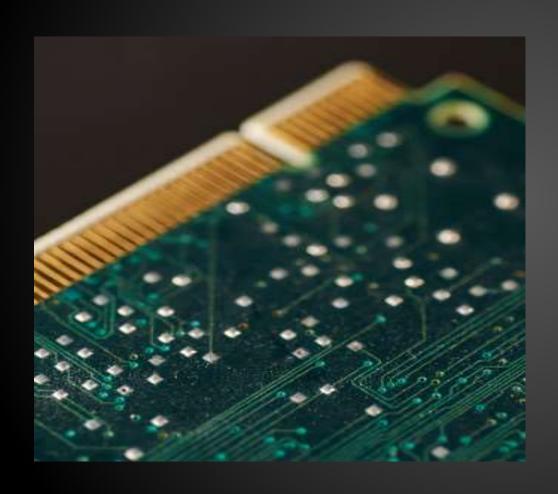












# Operational Performance



### Income Statement

NTD Thousand	2023Q3		2022Q3		2023Q1~Q3		2022Q1~Q3	
	Amount	%	Amount	%	Amount	%	Amount	%
OPERATING REVENUE	307,868	100.00	520,979	100.00	820,601	100.00	1,963,045	100.00
OPERATING COSTS	229,220	74.45	439,812	84.42	645,110	78.61	1,473,229	75.05
GROSS PROFIT	78,648	25.55	81,167	15.58	175,491	21.39	489,816	24.95
Selling and marketing expenses	37,112	12.05	27,477	5.27	92,271	11.24	117,422	5.98
General and administrative expenses	30,152	9.79	31,448	6.04	82,995	10.11	106,856	5.44
Research and development expenses	30,956	10.05	57,393	11.02	90,043	10.97	151,630	7.72
Expected credit impairment losses (gains)	(734)	(0.24)	(6,871)	(1.32)	(17,013)	(2.07)	9,667	0.49
OPERATING EXPENSES	97,486	31.66	109,447	21.01	248,296	30.26	385,575	19.64
OPERATING PROFIT(LOSSES)	(18,838)	(6.12)	(28,280)	(5.43)	(72,805)	(8.87)	104,241	5.31
NON-OPERATING INCOME AND EXPENSES	25,187	8.18	47,486	9.11	63,748	7.77	272,021	13.86
PROFIT BEFORE INCOME TAX	6,349	2.06	19,206	3.69	(9,057)	(1.10)	376,262	19.17
NET PROFIT FOR THE PERIOD	9,279	3.01	16,743	3.21	(9,020)	(1.10)	323,848	16.50
BASIC EARNINGS PER SHARE(NTD)	0.11		0.21		(0.10)		3.94	

### Thank You!

Ta Liang Technology Co., Ltd.